

DATE 22 JAN 2015

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL TIP.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.45 0.55		
A1	0.00	0.05	
А3	0.125 REF		
b	0.20	0.30	
D	3.00 BSC		
D2	2.40	2.60	
E	3.00 BSC		
E2	1.60	1.80	
е	0.50 BSC		
K	0.20		
L	0.30	0.50	
L2	0.15 REF		

GENERIC MARKING DIAGRAM*



= Assembly Location Α

= Wafer Lot = Year W = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

*For additional	information on our Pb-Free strategy and soldering
details, pleas	e download the ON Semiconductor Soldering and
Mounting Tec	hniques Reference Manual, SOLDERRM/D.

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